# **N-Channel Power MOSFET 60 V, 43 A, 18 m**Ω

### Features

- Low Gate Charge
- Fast Switching
- High Current Capability
- 100% Avalanche Tested
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter Symbol Value Unit						
Parar	Symbol	value	Unit			
Drain-to-Source Voltag	V <sub>DSS</sub>	60	V			
Gate-to-Source Voltag	e – Contir	nuous	V <sub>GS</sub>	±20	V	
Gate–to–Source Voltage – Non–Repetitive (t <sub>p</sub> < 10 μs)			V <sub>GS</sub>	±30	V	
Continuous Drain		$T_{C} = 25^{\circ}C$	Ι <sub>D</sub>	43	А	
Current (R <sub>θJC</sub> )	Steady	$T_C = 100^{\circ}C$		31		
Power Dissipation $(R_{\theta JC})$	State	$T_C = 25^{\circ}C$	P <sub>D</sub>	71	W	
Pulsed Drain Current	t <sub>p</sub> =	= 10 μs	I <sub>DM</sub>	192	А	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	–55 to 175	°C	
Source Current (Body I	۱ <sub>S</sub>	43	А			
Single Pulse Drain-to-Source L = 0.1 mH Avalanche Energy			E <sub>AS</sub>	36	mJ	
			I <sub>AS</sub>	27	А	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\thetaJC}$	2.1	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\thetaJA}$	49	

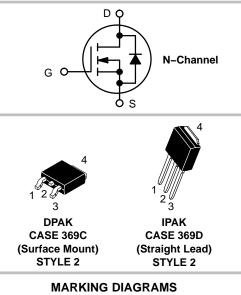
1. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.



### **ON Semiconductor®**

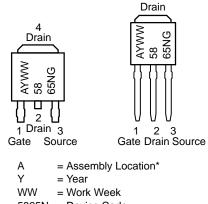
### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX	
60 V	18 mΩ @ 10 V	43 A	



# **& PIN ASSIGNMENT**

4



5865N = Device Code = Pb-Free Package

G

\* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

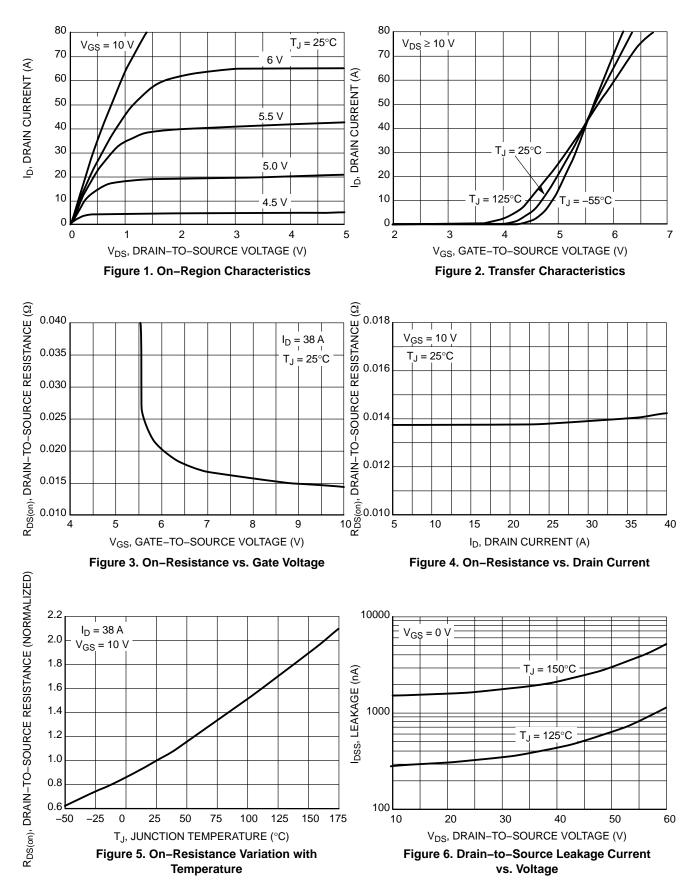
### **ORDERING INFORMATION**

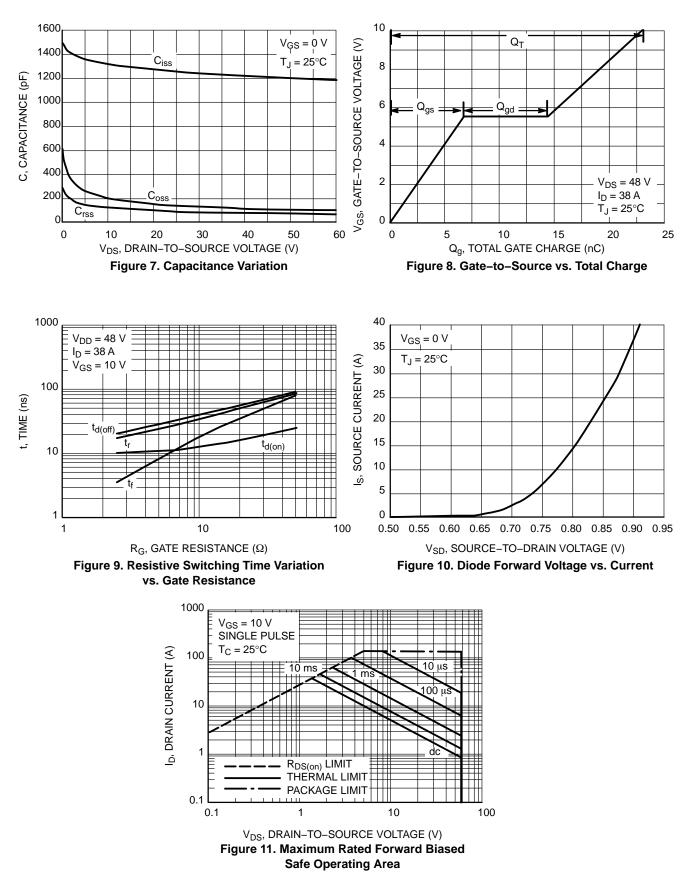
See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

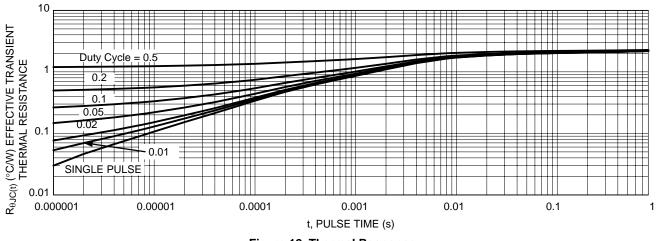
### ELECTRICAL CHARACTERISTICS (T<sub>1</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS						•	-	
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				59.2		mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$			1.0	μΑ	
		$V_{DS} = 60 \text{ V}$	T <sub>J</sub> = 150°C			100		
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS}$	s = ±20 V			±100	nA	
ON CHARACTERISTICS (Note 2)								
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D$	= 250 μA	2.0		4.0	V	
Negative Threshold Temperature Co- efficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				8.6		mV/°C	
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>E</sub>	) = 20 A		14	18	mΩ	
Forward Transconductance	gFS	V <sub>DS</sub> = 15 V, I <sub>E</sub>	) = 20 A		6.9		S	
CHARGES, CAPACITANCES AND GAT	E RESISTANCE	S						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 25 V			1261		pF	
Output Capacitance	C <sub>oss</sub>				136			
Reverse Transfer Capacitance	C <sub>rss</sub>				85			
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 48 V, I <sub>D</sub> = 38 A			23		nC	
Threshold Gate Charge	Q <sub>G(TH)</sub>				1.5			
Gate-to-Source Charge	Q <sub>GS</sub>				6.7			
Gate-to-Drain Charge	Q <sub>GD</sub>				7.7			
Gate Resistance	R <sub>G</sub>				1.5		Ω	
SWITCHING CHARACTERISTICS (Not	e 3)						-	
Turn–On Delay Time	t <sub>d(on)</sub>				10		ns	
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 10 V, V <sub>D</sub>	<sub>D</sub> = 48 V,		17		1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_{\rm D} = 38 \text{A},  \text{R}_{\rm G} = 2.5 \Omega$			20		1	
Fall Time	t <sub>f</sub>				3.5			
DRAIN-SOURCE DIODE CHARACTER	ISTICS							
Forward Diode Voltage	VGS = 0 V,	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.94	1.2	V	
		T <sub>J</sub> = 125°C		0.85		1		
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dls/dt = 100 A/μs, I <sub>S</sub> = 38 A			23		ns	
Charge Time	ta				17		1	
Discharge Time	tb				6		1	
Reverse Recovery Charge	Q <sub>RR</sub>				20		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2%. 3. Switching characteristics are independent of operating junction temperatures.







### Figure 12. Thermal Response

### **ORDERING INFORMATION**

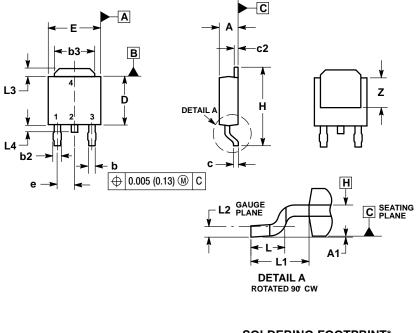
Order Number	Package	Shipping <sup>†</sup>
NTD5865N–1G	IPAK (Straight Lead) (Pb-Free)	75 Units / Rail
NTD5865NT4G	DPAK (Pb–Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS

### DPAK (SINGLE GUAGE) CASE 369AA

**ISSUE B** 



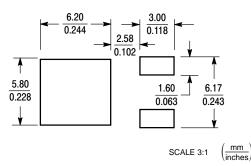
NOTES:

- IOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: INCHES.
  3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS 53, L3 and Z.

- A DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
   DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

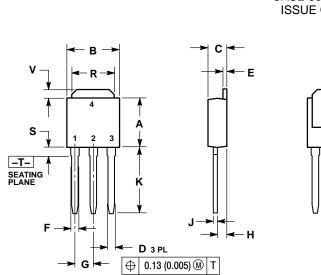
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	REF	2.74	REF	
L2	0.020	BSC	0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		
STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN					

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS



**IPAK** CASE 369D **ISSUE C** 

Ζ

NOTES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.35	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.090 BSC		2.29 BSC		
н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
Κ	0.350	0.380	8.89	9.65	
R	0.180	0.215	4.45	5.45	
S	0.025	0.040	0.63	1.01	
V	0.035	0.050	0.89	1.27	
Ζ	0.155		3.93		

STYLE 2: PIN 1. GATE 2. DRAIN SOURCE 3. 4 DRAIN

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